

~~surface of a projection on the first surface to make the layer-to-layer~~  
~~connection of said multilayer circuit, for electrically conducting said~~  
~~conductive layer of one of said circuit layers to said conductive layer of~~  
~~another one of said circuit layers, wherein when said multilayer circuit is~~  
~~on the first surface, said conductive layer of one of said circuit layers is~~  
~~electrically connected to said conductive layer of another one of said~~  
~~circuit layers by said second conductive layer on the side surface of said~~  
~~projection as the second surface; and~~  
  
~~when said multilayer circuit is on the level surface of the second surface of said~~  
~~substrate, said conductive layer of one of said circuit layers is electrically~~  
~~connected to said conductive layer of another one of said circuit layers by~~  
~~said second conductive layer on the second surface extending from the end~~  
~~of the first surface at an obtuse angle.~~  
  
~~wherein the first surface is a top surface of said substrate, and the second surface~~  
~~further includes a side surface of said substrate, and~~  
  
~~wherein the required angle between the first and second surfaces is an obtuse~~  
~~angle.~~

8. (Currently Amended) A multilayer circuit board comprising:

- a substrate having a first surface and a projection formed on the first surface, a side surface of said projection extending at an obtuse angle relative to the first surface;
- a pair of multilayer circuits formed on the first surface at both sides of said projection, each of said multilayer circuits composed of a plurality of

circuit layers, each of which is provided with a conductive-metal layer having a required circuit pattern and an insulation layer formed on said conductive-metal layer by film formation; and

a second conductive-metal layer successively formed on side and top surfaces of said projection,

wherein said conductive-metal layer of one of said circuit layers is electrically connected to said conductive layer of another one of said circuit layers by said second conductive-metal layer on the side surface of said projection, and simultaneously one of the pair of multilayer circuits is electrically connected to the other one by said second conductive-metal layer on the side and top surfaces of said projection, .

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~~wherein an angle between the side surface of said projection and the first surface is an obtuse angle.~~

9. (Previously Presented) The multilayer circuit board as set forth in claim 8, wherein said multilayer circuit has an aperture, through which a part of the first surface is exposed, and an electronic device is mounted in a concave formed in the exposed first surface, and an electrical connection between said multilayer circuit and said electronic device is made by a third conductive-metal layer formed on an inner surface of said concave.

10. (Previously Presented) The multilayer circuit board as set forth in claim 8, wherein said second conductive-metal layer is a plurality of second conductive layers to obtain plural layer-to-layer connections of said multilayer circuit, and each of second